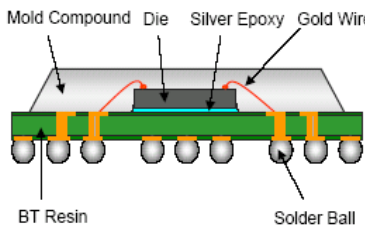


Material Declaration

Compliance Date: Feb./24/2022

RoHS Compliance: Yes

MSL: 3

Pin count /Package		48B BGA (Stacked)							
Model (Part) Number		AS6C1608B-45BIN							
Package Weight (mg)		120.62							
Composed parts	Purpose	Weight (mg)	%	ppm	Material	CAS No.	Weight (mg)	Material wt% of total Mass	Material wt% of Sub part
Chip	Wafer Circuit	14	11.61	116,067	Silicon (Si)	7440-21-3	14.000	11.607%	100.00%
Bonding Wire	Conductivity	0.65	0.54	5,389	Gold (Au)	7440-57-5	0.650	0.539%	100.00%
Die Attach	Die Attach	0.43	0.36	3,565	Synthetic rubber	(Trade secret)	0.009	0.007%	2.00%
					Silicon, amorphous	7631-86-9	0.086	0.071%	20.00%
					Phenol resin	(Trade secret)	0.043	0.036%	10.00%
					Epoxy resin	(Trade secret)	0.043	0.036%	10.00%
					Polypropylene copolymer (Dicing tape)	(Trade secret)	0.180	0.149%	41.90%
					Acrylic resin	(Trade secret)	0.052	0.043%	12.00%
					Polyethylene copolymer	(Trade secret)	0.018	0.015%	4.10%
Substrate	Substrate	40.46	33.543	335434	Barium Sulfate	7727-43-7	2.913	2.415%	7.20%
					Dipropylene glycolmonomethyl ether	34590-94-8	1.554	1.288%	3.84%
					Talc containing noasbestiform fibers	14807-96-6	0.259	0.215%	0.64%
					Epoxy resin	Trade seacret	1.424	1.181%	3.52%
					Morpholine derivative	Trade seacret	0.259	0.215%	0.64%
					Naphthalene	91-20-3	0.065	0.054%	0.16%
					Cured thermosettingresin (includinginorganic filler)	Trade seacret	10.135	8.403%	25.05%
					Continuous FilamentFiber Glass	Trade seacret	6.672	5.531%	16.49%
					Bisphenol A Epoxy Resin	80-05-7	0.085	0.070%	0.21%
					Copper	7440-50-8	16.540	13.713%	40.88%
					Gold	7440-57-5	0.065	0.054%	0.16%
Nickel	7440-02-0	0.490	0.406%	1.21%					
Molding Compound	Chip Protection	56.38	46.74	467,418	Silica (Fused)	60676-86-0	50.460	41.834%	89.50%
					Epoxy resin	(Trade secret)	2.819	2.337%	5.00%
					Phenol resin	(Trade secret)	2.819	2.337%	5.00%
					Carbon Black	1333-86-4	0.282	0.234%	0.50%
Solder Ball	Solder	8.70	7.21	72,127	Tin (Sn)	7440-31-5	8.396	6.960%	96.50%
					Silver (Ag)	7440-22-4	0.261	0.216%	3.00%
					Copper (Cu)	7440-50-8	0.044	0.036%	0.50%